Substrate Compatibility Test Report

Date: 6/29/10
Material: Label
Machine: WS6000 / Nr.
Location: RIT
Certification Number: RI6000-10-1821

SUBSTRATE TEST DETAILS
Supplier name: Avery Dennison - FRNA
Media name: 60# Gloss ITC/S246/40#CK

<table>
<thead>
<tr>
<th>Category</th>
<th>Self-adhesive</th>
<th>Flexible Packaging</th>
<th>Paper</th>
<th>Shrink Sleeve</th>
<th>Synthetic</th>
<th>Magnetic</th>
<th>Cartonboard</th>
<th>IML</th>
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<td>× Other</td>
<td>× Canada</td>
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<td>Media type</td>
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Test description: Official substrate compatibility test for industrial presses WS6000.

Test procedure: Screen test × Full test

Shipping condition received goods: firmly wrapped and protected to stabilize environmental conditions

Setup (default): Ink version: 4.5
Blanket code: Telescopic: None
Pip code: Static: None
ITM default temperature: 105 degr. C.

Substrate behaviour: Bleeding: None
Telescopic: None
Static: None
Jams: None

Necessary print cleaners: 1
Ink adhesion: Pass
After 15 mins. = 98%
Magenta: ok
Yellow: ok
Black: ok

Forced colour test: Cyan: ok
Magenta: ok
Yellow: ok

Temperature mapping: 95 degr.= 100%
105 degr.= 100%
115 degr.= 100%

Press settings (best working point) PTH 55
Blanket= 105
Feed fan = 8
2nd Transfer = 250

Test result/conclusion: × PASS  FAIL

Additional remarks/comments: